

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all previous versions or listing of claims in the application.

Listing of Claims

1. (Currently Amended) A copper foil ~~provided with an ultra thin primer resin layer for securing good laminating adhesiveness with a resin base material on one side of a copper foil without roughening treatment, where in, a copper foil with an ultra thin adhesive layer for a printed wiring board is characterized in that~~ comprising a ultra thin primer resin layer of a converted thickness of 1 to 5 μm ~~[[is]]~~ provided on a surface of a copper foil, wherein said surface of the copper foil has not undergone a roughening treatment and has having a surface roughness (Rz) of 2 μm or less not undergone said roughening treatment, and wherein said ultra thin primer resin layer is formed using a resin mixture consisting of 20 to 80 parts by weight of an epoxy resin that may contain a curing agent, 20 to 80 parts by weight of a solvent-soluble aromatic polyamide resin polymer, and an effective amount of a curing accelerator.

2. (Original) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1, comprising a silane coupling agent layer on the surface of the copper foil provided with the ultra thin primer resin layer.

3. (Original) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 2, wherein said silane coupling agent layer is formed using an amino-based silane coupling agent or a mercapto-based silane coupling agent.

4. (Cancelled)

5. (Currently Amended) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1 ~~claim 4~~, wherein said aromatic polyamide polymer using for said ultra thin primer resin layer is obtained by allowing an aromatic polyamide to react with a ~~rubber-like~~ resin.

6. (Currently Amended) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1, wherein said ultra thin primer resin layer is formed using a resin mixture consisting of 5 to 50 parts by weight of an epoxy resin that may contain ~~(containing a curing agent [D])~~, 50 to 95 parts by weight of a polyether ~~sulfon~~ sulfone resin ~~(having a hydroxyl group or an amino group at an proximal end, and soluble in a solvent)~~, and an appropriate quantity added as required of a curing accelerator.

7. (Currently Amended) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1, wherein ~~[[the]]~~ a resin flow when measured in accordance with MIL-P-13949G in the MIL Standard is 5% or less.

8. (Currently Amended) A method for manufacturing a copper foil with an ultra thin adhesive layer for a printed wiring board comprising:
preparing characterized in that a resin solution by mixing an

~~used in the formation of an ultra thin primer resin layer is prepared by the procedures of the following Step a and Step b; and a converted thickness of 1 to 5 μm of said resin solution is applied onto a surface of a copper foil on which a silane coupling agent layer is formed, and dried to be in a semi-cured state comprising the Step a. and the Step b.:- Step a. An epoxy resin that may contain (containing a curing agent), an aromatic polyamide polymer soluble in a solvent, or a polyether sulfon sulfone resin, and an appropriate quantity added as required of a curing accelerator being mixed to form a resin mixture;:- Step b.~~

~~dissolving the Said resin mixture being dissolved using an organic solvent to form a resin solution of a resin solid content of 10% by weight to 40% by weight;~~

~~applying the resin solution onto a surface of a copper foil on which a silane coupling agent layer has been formed to form a resin layer; and~~

~~drying the resin layer to a semi cured state,~~

~~wherein the thickness of the resin layer is 1 to 5 μm .~~

9. (Currently Amended) A copper-clad laminate comprising using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1.

10. (Currently Amended) A copper-clad laminate comprising using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 2.

11. (Currently Amended) A copper-clad laminate comprising using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 3.

12. (Cancelled)

13. (Currently Amended) A copper-clad laminate comprising using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 5.

14. (Currently Amended) A copper-clad laminate comprising using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 6.

15. (Currently Amended) A copper-clad laminate comprising using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 7.

16. (New) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 6, wherein the polyether sulfone resin has a hydroxyl group or an amino group at a proximal end, and is soluble in a solvent.